

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

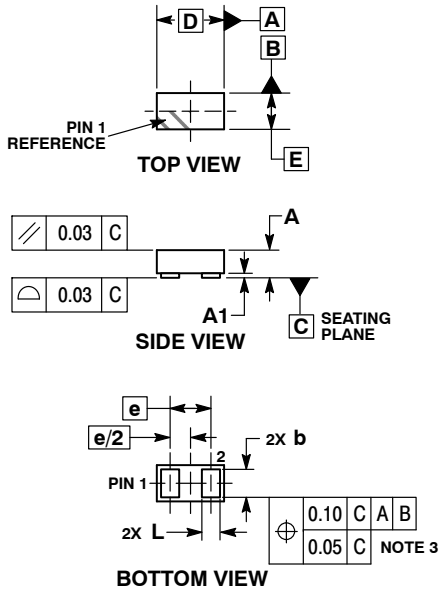
ON Semiconductor®



SCALE 10:1

X4DFN2, 0.445x0.24, 0.27P
CASE 718AA
ISSUE A

DATE 21 MAR 2017

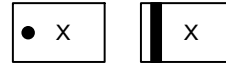


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. EXPOSED COPPER ALLOWED AS SHOWN.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.15	0.18	0.21
A1	---	---	0.03
b	0.170	0.185	0.200
D	0.415	0.445	0.475
E	0.210	0.240	0.270
e	0.270 BSC		
L	0.105	0.120	0.135

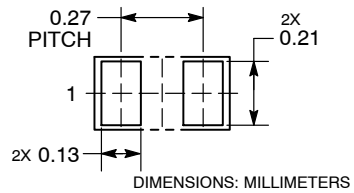
GENERIC MARKING DIAGRAMS*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT*



See Application Note AND8398/D for more mounting details
 *For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	X4DFN2, 0.445X0.24, 0.27P	PAGE 1 OF 1

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